GigaDevice Semiconductor Inc.

GD32VW553 Quick Development Guide

Application Note
AN154

Revision 1.3a

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1. Introduction to development board

1.1. Picture of real development board

1.1.1. The START development board

The START development board consists of a baseboard and a module equipped with the GD32VW55x Wi-Fi+BLE chip.

Figure 1-1. The picture of the START development board
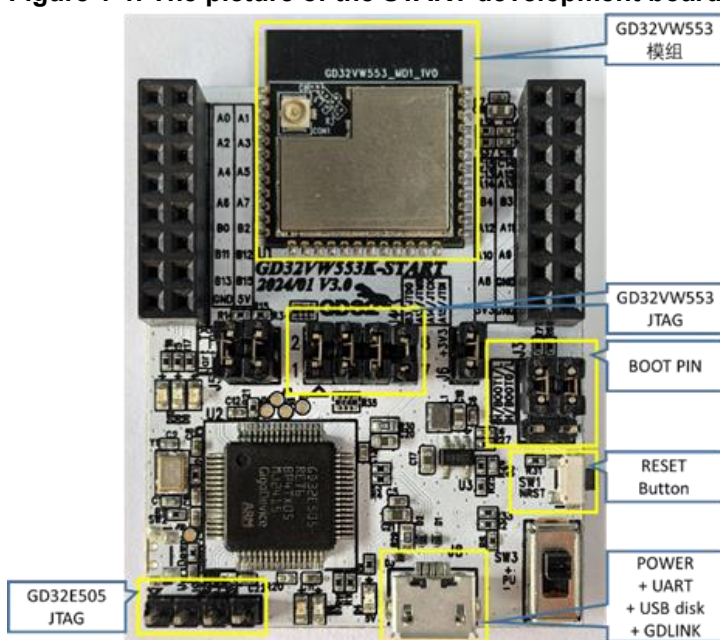
Mainly focus on the following parts of the development board, which have been marked in the *Figure 1-1. The picture of the START development board*.

- Boot mode (Boot PIN);
- Power supply port (POWER);
- View log (UART);
- Debugger interface (JLink, or GDLink);
- Reboot (Reset Button).

The START V4.0 and V4.1 development board support four wireless modules: GD32VW553_MD1, GD32VW553_MD2, GD32VW553-MINI-I, and GD32VW553-MINI-E. Among these four modules, the wireless main chip of the GD32VW553_MD1 module adopts a QFN40 package, while the wireless main chips of the other modules adopt a QFN32 package. The module model shown in the *Figure 1-1. The picture of the START development board* is GD32VW553_MD1, which has the same package and dimensions as GD32VW553_MD2. GD32VW553-MINI-I module and GD32VW553-MINI-E module are shown in *Figure 1-2. GD32VW553-MINI-I Module(Left)and GD32VW553-MINI-E*

Module(Right).

Figure 1-2. GD32VW553-MINI-I Module(Left)and GD32VW553-MINI-E Module(Right).
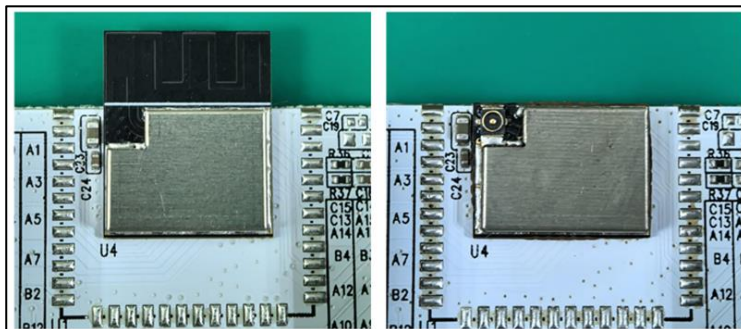
The connectors and switch functions of the START development board are shown in *Table 1-1. The START development board connectors and switch functions*.

Table 1-1. The START development board connectors and switch functions

Interface	Description
J1	Interface to GPIO pins PA0~PA7 / PB0 / PB15 of the main chip, as well as +5V interface and GND interface.
J2	Interface to main chip PA12~PA15 / PB3 / PB4 / PC13~PC15 GPIO pins, as well as module +3.3V power supply test interface, GND interface.
J3	Connect to the main chip PC8 (BOOT0) and PB1 (BOOT1) pins, Boot mode selection needs to be configured accordingly. Default Boot0 / 1 use shorting caps pull-down, that is, the chip default boot from Sip flash.
J4	Interface to the JTAG pins of PB3(JTDO) / PA13(JTMS) / PA14(JTCK) / PA15(JTDI) of the main chip, and interface to the JTAG pins of L_TDO / L_TMS / L_TCK / L_TDI of the GDLINK chip. By default, the above pins of the main chip and the GDLINK chip are connected by shorting caps, and the firmware can be burned into the main chip by the GDLINK chip.
J5	The interface to the UART T / RX pins of the main chip PA6 (UART2_TX) and PA7 (UART2_RX), and the interface to the L_UART_RX and L_UART_TX UART R / TX pins of the GDLINK chip. By default, the above pins of the main chip and the GDLINK chip are connected via shorting caps, so that serial communication can be done between the GDLINK chip and the main chip.
J6	GD32VW553 module 3.3V power supply connection port, the default use of short-circuit cap connection. For power consumption test, external 3.3V power supply can be directly connected to J6.2.
J8	USB-C interface, default serial communication and +5V power supply interface.
J9	Interface to GDLINK chip L_SWDIO / L_SWDCK / L_NRST and other SWD pins, as

Interface	Description
	well as GDLINK +3.3V power supply test interface and GND interface.
SW1	Connect the module to the NRST pin with GND via a 1K ohm resistor pull-up to 3.3 V. Press and release this switch to Reset the main chip.
SW2	Connect the GDLINK chip to the UART Download pin and GND via the 1K ohm resistor pull-up to 3.3V, press and hold the switch, connect the START development board to the PC via the USB cable, and then release the switch to copy/paste the firmware of the GDLINK chip to be burned.
SW3	Connect the module to the PU pin in series with +3.3V power supply (or GND) via a 1K ohm resistor. Switch up toggle, main chip power up, switch down toggle, main chip power down. For the START development board using the GD32VW553-MINI-I / E module, this switch is not available.

The main interfaces description of the START development board are described in _**Table 1-2. The START development board main interfaces description**_. For the V3.0 and earlier versions of the START development board, the GPIOs connected to the red, green, and blue LEDs are PB11/12/13, so the START development board with MD2 module cannot light up these three LEDs. However, in the new versions V4.0 and V4.1 of the START development board, the GPIOs connected to the red, green, and blue LEDs have been changed to PB0/PA12/PB4, so both MD2 and MINI modules can light up these three LEDs.

For more information about the START development board, you can refer to the GD32 official website's _**GD32VW553K-START Demo Suites**_ page and download the attached content.

Table 1-2. The START development board main interfaces description

Interface	Description
PA0	IO port that can be configured by the user.
PA1	IO port that can be configured by the user.
PA2	IO port that can be configured by the user.
PA3	IO port that can be configured by the user.
PA4	IO port that can be configured by the user.
PA5	IO port that can be configured by the user.
PA6 / UART2_TX	IO port that can be configured by the user; UART TX。
PA7 / UART2_RX	IO port that can be configured by the user; UART RX。
PB0	IO port that can be configured by the user.
PB1 / BOOT1	IO port that can be configured by the user; Boot mode selection.
PB2	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**

| Interface	Description
GND	Reference ground
PB11	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PB12	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PB13	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PB15	IO port that can be configured by the user.
PA8	IO port that can be configured by the user.
PA9	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PA10	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PA11	IO port that can be configured by the user. **This interface is not available for START development board with MD2 or MINI-I/E module.**
PA12	IO port that can be configured by the user.
PB3 / JTDO	IO port that can be configured by the user; JTDO pin.
PB4 / JNTRST	IO port that can be configured by the user; JNTRST pin.
PA13 / JTMS	IO port that can be configured by the user; JTMS pin.
PA14 / JTCK	IO port that can be configured by the user; JTCK pin.
PC8 / BOOT0	IO port that can be configured by the user; Boot mode select.
PA15 / JTDI	IO port that can be configured by the user; JTDI pin.
PC13	IO port that can be configured by the user. **This interface is not available for START development board with MINI-I/E module.**
PC14	IO port that can be configured by the user.
PC15	IO port that can be configured by the user.
NRST	Module enable pin, connect to 3.3V power supply to enable the module.
PU	Module enable pin, connect to 3.3V power supply to enable the module. **This interface is not available for START development board with MINI-I/E module.**
3V3	3.3V power supply pin
GND	Reference ground

1.1.2. The EVAL development board

The EVAL development board consists of a baseboard and a module equipped with the GD32VW55x Wi-Fi+BLE chip. The baseboard lead out many peripheral test ports, such as I2C, IFRP, ADC and so on.

Figure 1-3. The picture of the EVAL development board
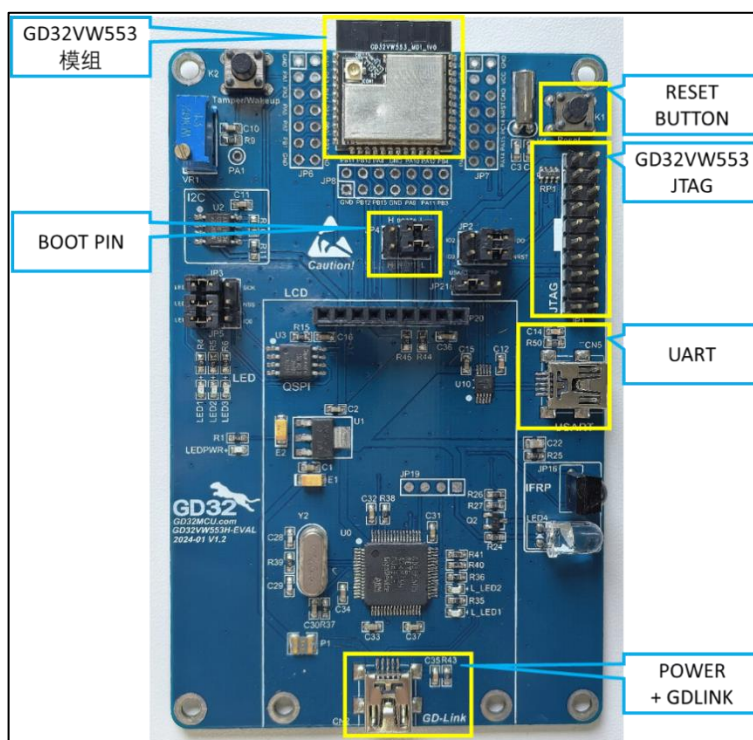
Developers mainly focus on the following parts of the development board, which have been marked in the *Figure 1-3. The picture of the EVAL development board*.

- Boot mode (Boot PIN);
- Power supply port (power supply);
- View log (UART);
- Debugger interface (JLink, or GDLink);
- Reboot (Reset Button).

For more information about the EVAL development board, you can refer to the GD32 official website's *GD32VW553 Demo Suites* page and download the attached content.

For the START development board and the EVAL development board, the SDK configuration is different and different macros need to be selected to enable them. As shown in *Figure 1-4. Development Board Type Configuration*, the SDK selects the START development board configuration as the default. The configuration file is GD32VW55x_RELEASE/config/ platform_def.h.

Figure 1-4. Development Board Type Configuration

```
// board type
#define PLATFORM_BOARD_32VW55X_START····0
#define PLATFORM_BOARD_32VW55X_EVAL·····1
#define PLATFORM_BOARD_32VW55X_F527·····2
#ifdef CONFIG_PLATFORM_ASIC
#define CONFIG_BOARD ·················PLATFORM_BOARD_32VW55X_START
#endif
```

1.2. Boot mode

GD32VW55x can boot from ROM, FLASH, or SRAM.

The level selection of the two pins BOOT0 and BOOT1 in the BOOT SWD box of the development board determines the boot mode. See *Table 1-3. Boot mode*. For more instructions on the boot mode, please refer to the document "GD32VW55x_User_Manual".

Table 1-3. Boot mode

EFBOOTLK	BOOT0	BOOT1	EFSB	Boot address	Boot area
0	0	-	0	0x08000000	SIP Flash
0	0	-	1	0x0BF46000	secure boot
0	1	0	-	0x0BF40000	Bootloader/ROM
0	1	1	-	0x20000000	SRAM
1	0	-	0	0x08000000	SIP Flash
1	0	-	1	0x0BF46000	Secure boot
1	1	-	-	0x0BF40000	Bootloader/ROM

1.3. Debugger interface

For START development board, it comes with a GDLink(GD32E505) debugger that can be used with OpenOCD. Can also use an external debugger (GDLink or JLink) at the JTAG interface of the board for debugging and download. The GD32E505 chip also integrates the UART function, so only one USB cable is required to supply power, debug, and view the log. Connect the pins JCLK, JTWS, JTDO and JTDI to the middle four pins through jumper caps, and then download and debug the code through DAPLINK. *Figure 1-1. The picture of the START development board* shows how to debug through DAPLINK.
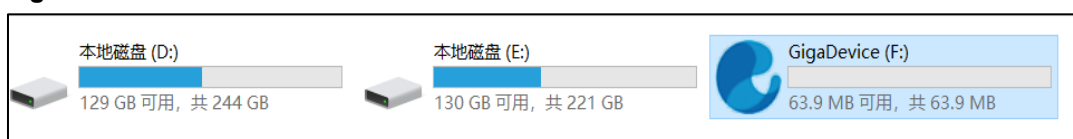
For EVAL development board, GDLink or JLink debugger can be used for debugging and download.

It should also be noted that the GD32VW55x supports cJTAG and JTAG but does not support the SWD debugging interface.

1.4.   Download interface

For the START development board, in addition to using the GDLink debugger or JLink debugger mentioned in the previous section for firmware downloading, if debugging functionality is not required and only firmware downloading is needed, the firmware can also be downloaded using a USB drive copy method. Connect the development board to a computer via a USB cable, as shown in ***Figure 1-5. List of devices and drivers***, under the devices and drives list as the GigaDevice drive. Copy the "image-all.bin" file (refer to subsequent sections) into the GigaDevice drive to complete the FLASH programming of the GD32VW55x chip.

Figure 1-5. List of devices and drivers

For EVAL development board, GDLink or JLink debugger can be used for download. Dragging into the USB disk is not supported.

1.5.   Viewing log

Connect a MicroUSB cable to the START development board, use a serial port tool on the PC, and configure it according to the parameters in ***Figure 1-6. Configuration of serial port*** and connect to the board. After that, use the serial port to output logs.

Figure 1-6. Configuration of serial port
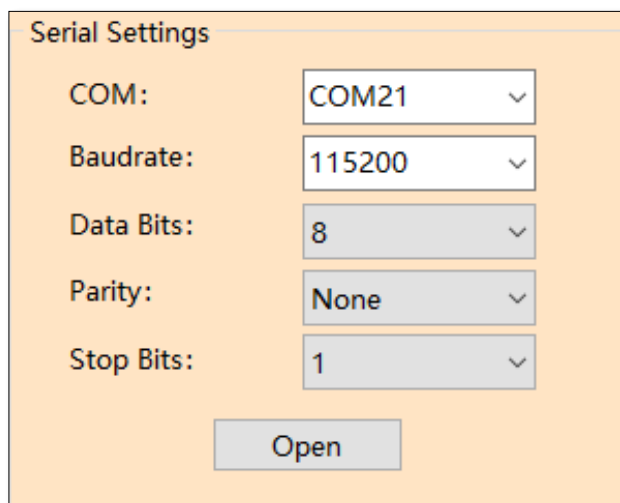
2. Building development environment

Build a development environment before compiling and downloading the firmware.

The development tool currently used is GD32 Embedded Builder and SEGGER Embedded Studio IDE.

2.1. Installation of GD32 Embedded Builder

The GD32 Embedded Builder can select GD32VW5 at website: **https://gd32mcu.com/cn/download** to download. The uncompress downloaded files is as **Figure 2-1 The Directory Structure of GD32 Embedded Builder** shows. The build tool, tool chain, openocd, jlink, and other related tools have all been placed in the Tools directory.

Figure 2-1 The Directory Structure of GD32 Embedded Builder
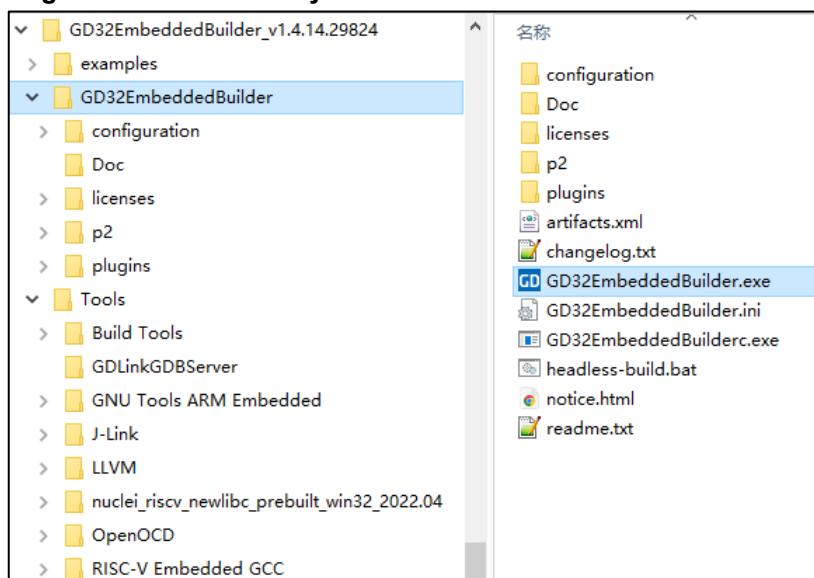
2.2. Installation of SEGGER Embedded Studio IDE

Please visit the website: https://wiki.segger.com/GD32V for how to get the SEGGER Embedded Studio IDE and License Activation Key.

3. What developers must know

Before getting started with development, first understand the members of the SDK execution program group, how to correctly configure the SDK.

3.1. SDK execution program group

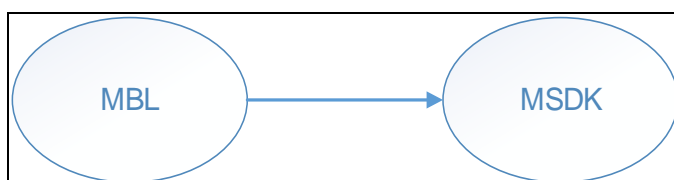SDK will finally generate two main execution programs: MBL (Main Bootloader) and MSDK (Main SDK), which will eventually be downloaded to FLASH to run. After power-on, the programs will boot from Reset_Handler of MBL, and then jump to the MSDK main program to run, as shown in **_Figure 3-1. Boot process_**.

Figure 3-1. Boot process

3.2. SDK configuration

3.2.1. Configuration of wireless module

The configuration file is GD32VW55x_RELEASE/config/platform_def.h, whose main content is as shown in **_Figure 3-2. Configuration of wireless module_**.

Figure 3-2. Configuration of wireless module

```
#define CFG_WLAN_SUPPORT
#define CFG_BLE_SUPPORT
#if defined(CFG_WLAN_SUPPORT) && defined(CFG_BLE_SUPPORT)
  #define CFG_COEX
#endif
```

■ In the case of BLE/ WiFi combo mode, please enable:
  – #define CFG_WLAN_SUPPORT
  – #define CFG_BLE_SUPPORT
■ In the case of BLE only, please only enable:
  – #define CFG_BLE_SUPPORT
■ In the case of WiFi only, please only enable:
  – #define CFG_WLAN_SUPPORT
■ To disable the wireless module, please disable all

3.2.2. SRAM layout

The configuration file is GD32VW55x_RELEASE\config\config_gdm32.h. Modify the following macro definition (as **_Figure 3-3. SRAM layout_** shows) values to plan the SRAM space occupied by the executable program segments MBL and IMG. These values are offset addresses, and the base address is defined at the beginning of the file.

The line marked "!Keep unchanged!" cannot be modified; otherwise, the operation of the MbedTLS code in the ROM will be affected.

Figure 3-3. SRAM layout

```
/* SRAM LAYOUT */
#define RE_MBL_DATA_START       0x300           /* !Keep unchanged! */
#define RE_IMG_DATA_START       0x200           /* !Keep unchanged! */
```

For the planning of SRAM space in each executable program segment, refer to the .ld file under the corresponding project, such as MBL\project\eclipse\mbl.ld and MSDK\plf\riscv\env\gd32vw55x.ld.

3.2.3. FLASH layout

The configuration file is GD32VW55x_RELEASE\config\config_gdm32.h. Modify the following macro definition(as **_Figure 3-4. FLASH layout_** shows) values to plan the FLASH space occupied by the executable program segments MBL and MSDK. These values are offset addresses, and the base address is defined at the beginning of the file.

The line marked "!Keep unchanged!" cannot be modified; otherwise, the operation of the project will be affected.

Figure 3-4. FLASH layout

```
/* FLASH LAYEROUT */
#define RE_VTOR_ALIGNMENT       0x200           /* !Keep unchanged! */
#define RE_SYS_SET_OFFSET       0x0             /* !Keep unchanged! */
#define RE_MBL_OFFSET           0x0             /* 0x0: Boot from MBL, 0x1000: Boot from ROM */
#define RE_SYS_STATUS_OFFSET    0x8000          /* !Keep unchanged! */
#define RE_IMG_0_OFFSET         0xA000          /* !Keep unchanged! */
#define RE_IMG_1_OFFSET         0x1E0000
#define RE_IMG_1_END            0x3CB000        /* reserved 192KB for user data */
#define RE_NVDS_DATA_OFFSET     0x3FB000        /* reserved 20KB for nvds data */
#define RE_END_OFFSET           0x400000        /* equal to flash total size */
```

For the planning of FLASH space in each executable program segment, refer to the .ld file under the corresponding project, such as MBL\project\eclipse\mbl.ld and MSDK\plf\riscv\env\gd32vw55x.ld.

3.2.4. Firmware version No.

The configuration file is GD32VW55x_RELEASE\config\config_gdm32.h. Modify the following

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macro definition values showed in *Figure 3-5. Firmware version No.* to specify the version No. In addition, the macro RE_IMG_VERSION is used in Securt Boot to determine the firmware version.

MBL only supports local upgrade, while IMG supports online upgrade. The version No. released by the SDK is consistent with RE_IMG_VERSION.

Figure 3-5. Firmware version No.

```
/* FW_VERSION */
#define RE_MBL_VERSION          0x01000003
#define RE_IMG_VERSION          0x01000003
```

3.2.5.   APP configuration

The configuration file is GD32VW55x_RELEASE\MSDK\app\app_cfg.h. Choose whether to enable some applications, such as ATCMD, Alibaba Cloud, MQTT, COAP and so on.

By modifying the macro CONFIG_BLE_LIB in app_cfg.h, the BLE library can be switched. When CONFIG_BLE_LIB is set to BLE_LIB_MIN (as shown in *Figure 3-6 BLE library selection*), the project compilation will use libble.a, and the header file will include ble_config_min.h. When CONFIG_BLE_LIB is set to BLE_LIB_MAX, the project compilation will use libble_max.a, and the header file will include ble_config_max.h.

Figure 3-6 BLE library selection

```
#define BLE_LIB_MIN                    0        //only peripharal and server
#define BLE_LIB_MAX                    1        //add central and client usage

#define CONFIG_BLE_LIB                BLE_LIB_MIN
```

The features supported by libble.a are as follows:

1. Supports peripheral

2. Supports a single connection link

3. Supports server

4. Supports host and controller

5. Supports EATT

6. Supports WeChat applet WiFi provisioning

Based on libble.a, libble_max.a additionally supports the following features:

1. Supports central

2. Supports four connection links

3. Supports client

4. Supports periodic advertising

5. Supports PHY updates

6. Supports power control

7. Supports BLE ping

8. Supports secure connection

3.2.6. Configuration Selection

The main project-MSDK, supports multiple configurations, with msdk selected by default. Additional options include msdk_ffd, msdk_mbedtls_2.17.0, msdk_rtthread, and msdk_threadx.

The main difference between msdk_ffd and msdk lies in the WiFi connection management library included in the project. The msdk includes libwpas, which is more streamlined and consumes fewer memory resources. The msdk_ffd includes wpa_supplicant, which is more comprehensive and general-purpose but has a larger codebase and consumes more memory resources. Additionally, msdk_ffd includes libble_max.a by default, enabling more BLE features. Of course, msdk can switch between libble.a and libble_max.a by modifying the configuration.

The main difference between msdk_mbedtls_2.17.0 and msdk lies in the version of the MbedTLS library included in the project. The msdk includes MbedTLS 3.6.2, which runs in FLASH. The msdk_mbedtls_2.17.0 includes MbedTLS 2.17.0, with most of its content running in ROM. If strict security requirements are needed, it is recommended to choose msdk. If FLASH space is limited, it is recommended to choose msdk_mbedtls_2.17.0

The main difference between msdk_rtthread and msdk lies in the RTOS used in the project. The msdk uses FreeRTOS. The msdk_rtthread uses RT-Thread.

The main difference between msdk_threadx and msdk also lies in the RTOS used in the project. The msdk uses FreeRTOS. The msdk_threadx uses ThreadX.

- msdk

  FreeRTOS + Libwpas.a + libble.a + MbesTLS 3.6.2

- msdk_ffd

  FreeRTOS + wpa_supplicant.a + libble_max.a + MbesTLS 3.6.2

- msdk_mbedtls_2.17.0

  FreeRTOS + Libwpas.a + libble.a + ROM MbesTLS 2.17.0

- msdk_rtthread

  RTThread + Libwpas.a + libble.a + MbesTLS 3.6.2

- msdk_threadx

  Threadx + Libwpas.a + libble.a + MbesTLS 3.6.2

For details on how to make configuration selection for actual use, see the Compiling MSDK Projects section in subsection *4.2Compilation*.

3.3.   Correct log example

After the firmware group (MBL+MSDK) is successfully downloaded, open the serial port tool, and press the Reset button on the development board. The startup information is shown in *Figure 3-7. Project boot information*. If an exception occurs, please check *6FAQ*for help.

Figure 3-7. Project boot information

```
ALW: MBL: First print.
ALW: MBL: Boot from Image 0.
ALW: MBL: Validate Image 0 OK.
ALW: MBL: Jump to Main Image (0x0800a000).
=== RF initialization finished ===
SDK Version: v1.0.3a-86d78d058d779fad
Build date: 2025/05/14 16:29:11
=== WiFi calibration done ===
=== PHY initialization finished ===
BLE local addr: AB:89:67:45:23:01, type 0x0
=== BLE Adapter enable complete ===
```

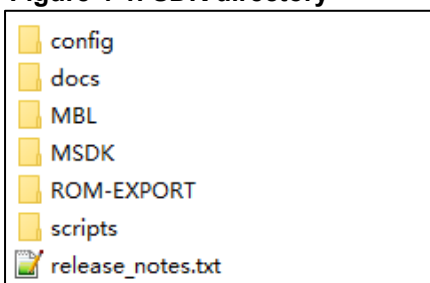# 4. GD32 Embedded Builder IDE project

This chapter introduces how to compile and debug the SDK under Embedded Builder IDE.

The project group consists of two projects: MBL/MSDK. MSDK includes Wi-Fi protocol stack, BLE protocol stack, peripheral drivers, applications, etc. The MBL is mainly responsible for selecting the correct MSDK firmware from the two (current firmware and OTA firmware) to run.

4.1. Opening the project group

Check the SDK directory GD32VW55x_RELEASE, as shown in **_Figure 4-1. SDK directory_**.

Figure 4-1. SDK directory

To start the IDE, double-click Embedded Builder.exe in the Embedded Builder directory, and select the SDK directory GD32VW55x_RELEASE as the workspace, and then click the launch button, as shown in **_Figure 4-2. Starting GD32 Embedded Builder IDE_**.

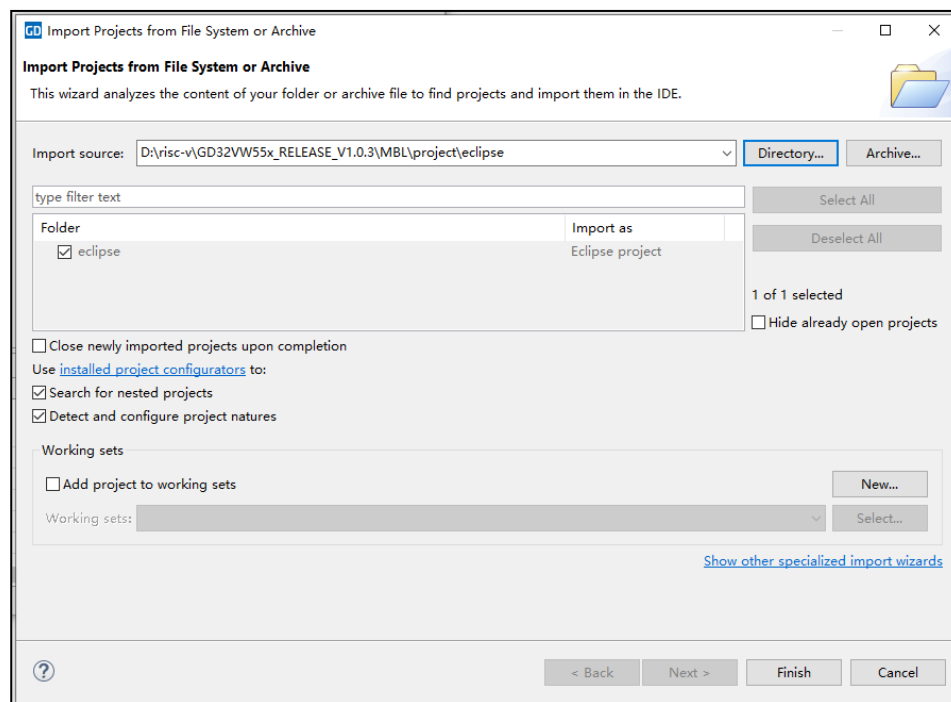**Figure 4-2. Starting GD32 Embedded Builder IDE**
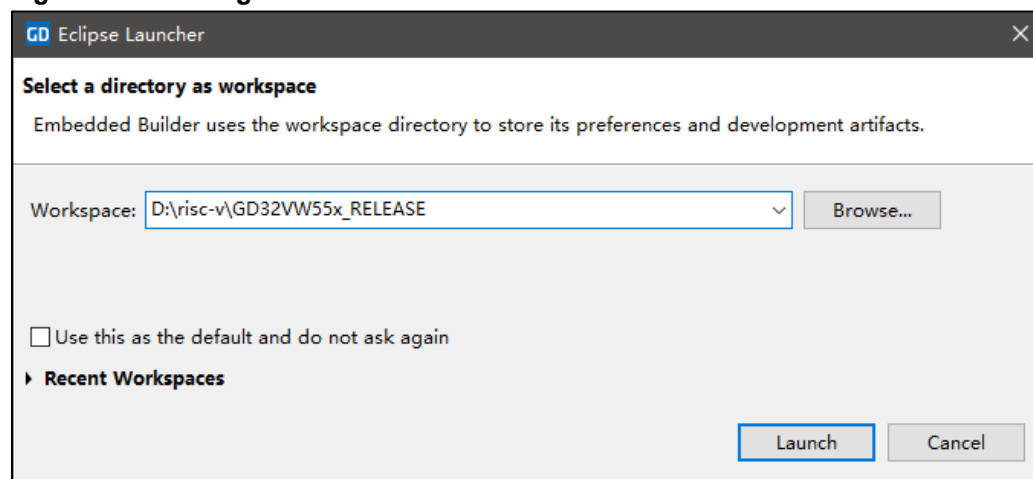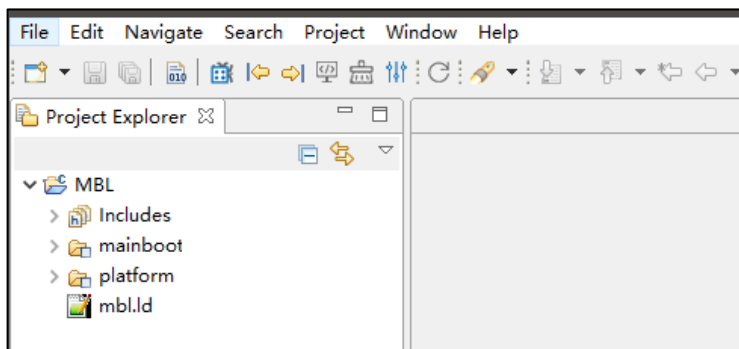

■ Import the MBL project

In the File menu, click Open Projects from file System, as shown in **_Figure 4-3. Open Projects from file System_**.

Figure 4-3. Open Projects from file System
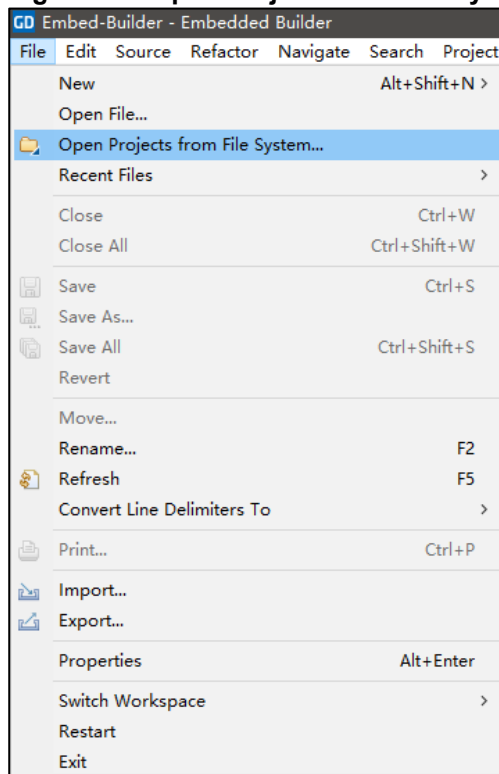
Select the project path GD32VW55x_RELEASE\MBL\project\eclipse, as shown in *Figure 4-4. Selecting MBL project path*, and click Finish.

Figure 4-4. Selecting MBL project path

Close the welcome interface, and the MBL project is shown as *Figure 4-5. MBL project interface* shows.

Figure 4-5. MBL project interface

■ Import the MSDK project

In the File menu, click Open Projects from file System, Select the project path GD32VW55x_RELEASE\MSDK\projects\eclipse\msdk, as shown in ***Figure 4-6. Selecting MSDK project path***, and click Finish.

Figure 4-6. Selecting MSDK project path
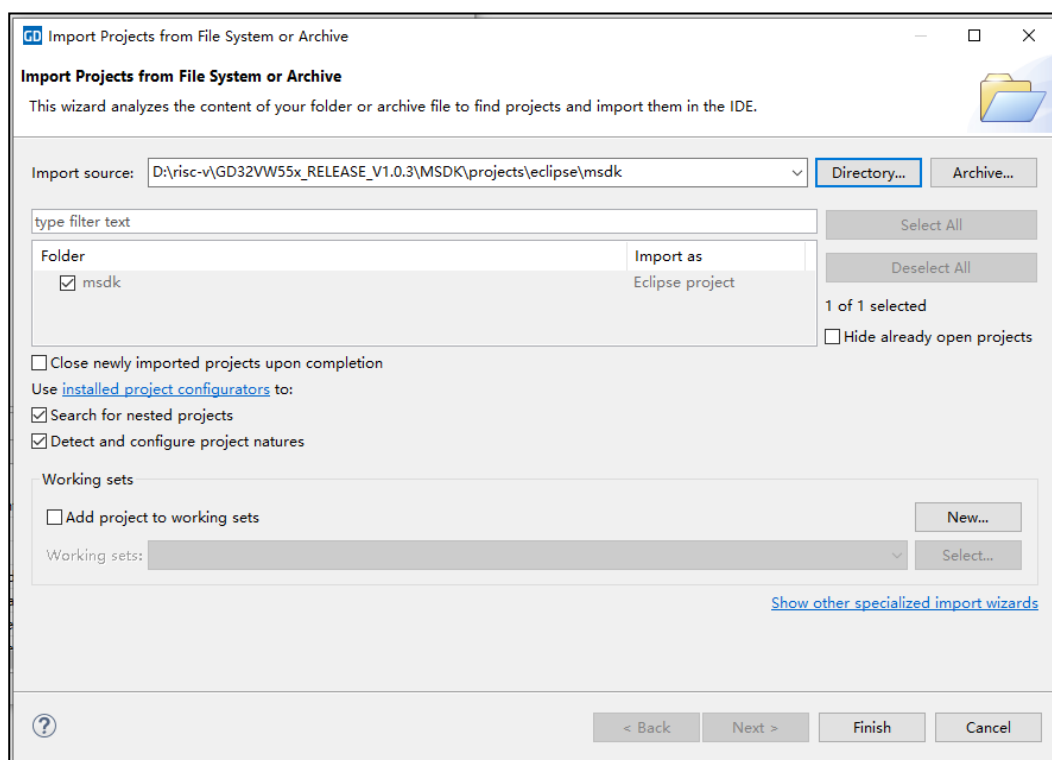
View the MSDK and MBL project interfaces, as shown in ***Figure 4-7. MSDK and MBL project interfaces***.

Figure 4-7. MSDK and MBL project interfaces
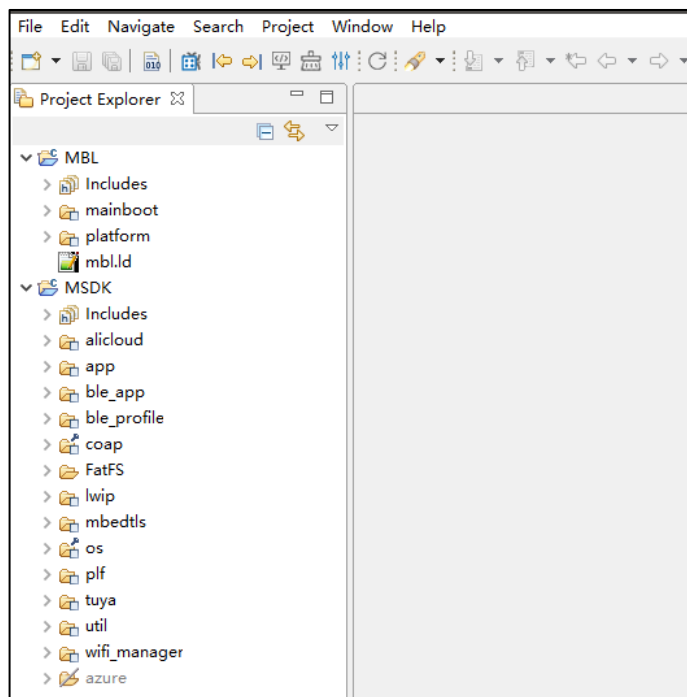
4.2. Compilation

■ Check the configuration of the project compilation tool

Right-click on the project, click on properties, select C/C++ Build -> Settings in order, and on the tab click on toolchain settings., as shown in *Figure 4-8. Properties of the project*.

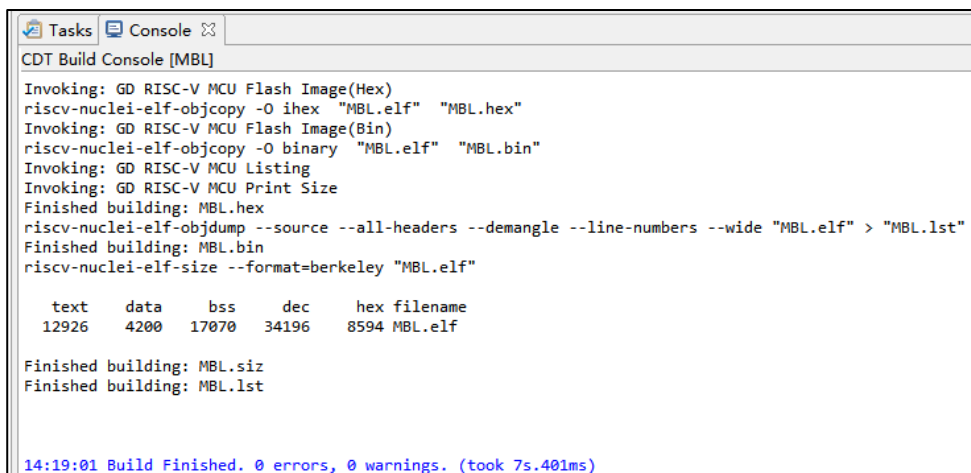**Figure 4-8. Properties of the project**
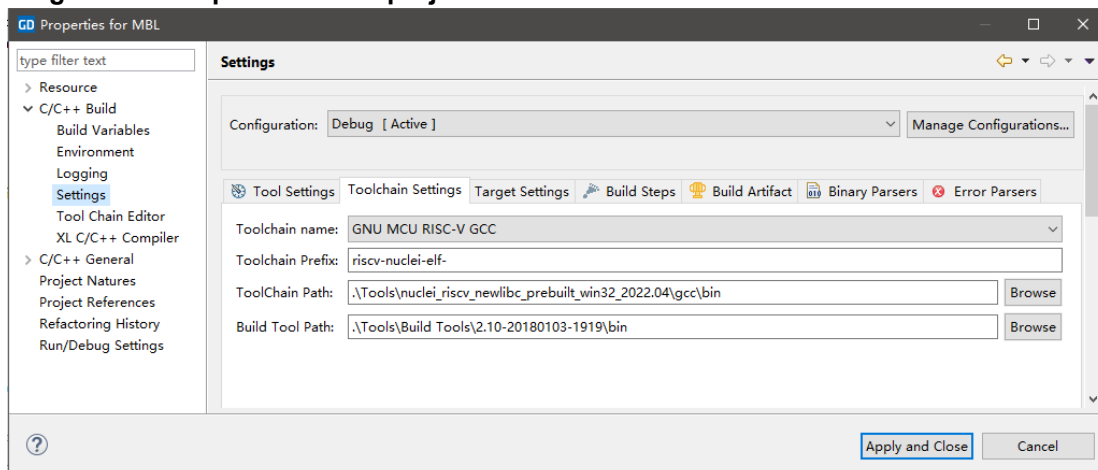
■ Compile the MBL project

Right-click the project, and click Build Project, as shown in *Figure 4-9. Compiling the MBL project*.

Figure 4-9. Compiling the MBL project
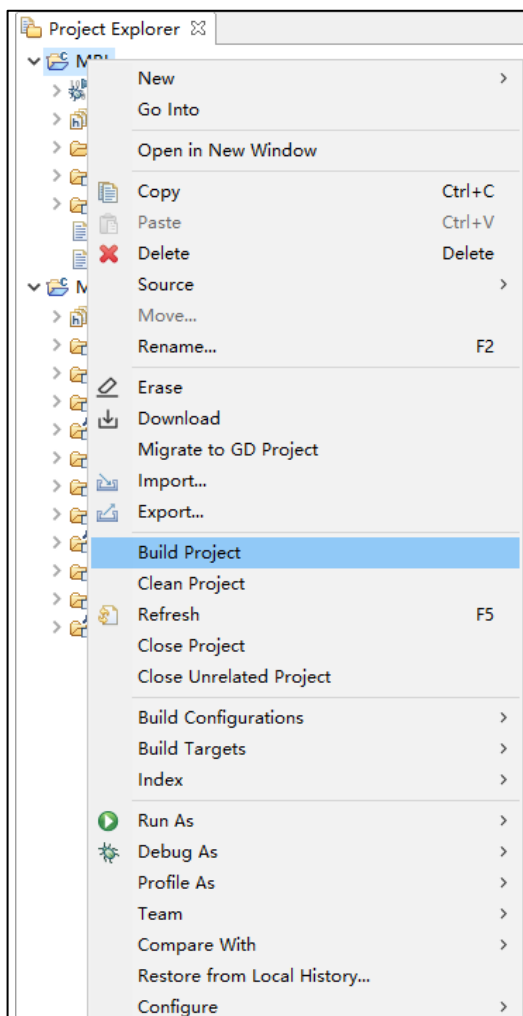
The compilation result is as shown in **_Figure 4-10. MBL compilation result_**.
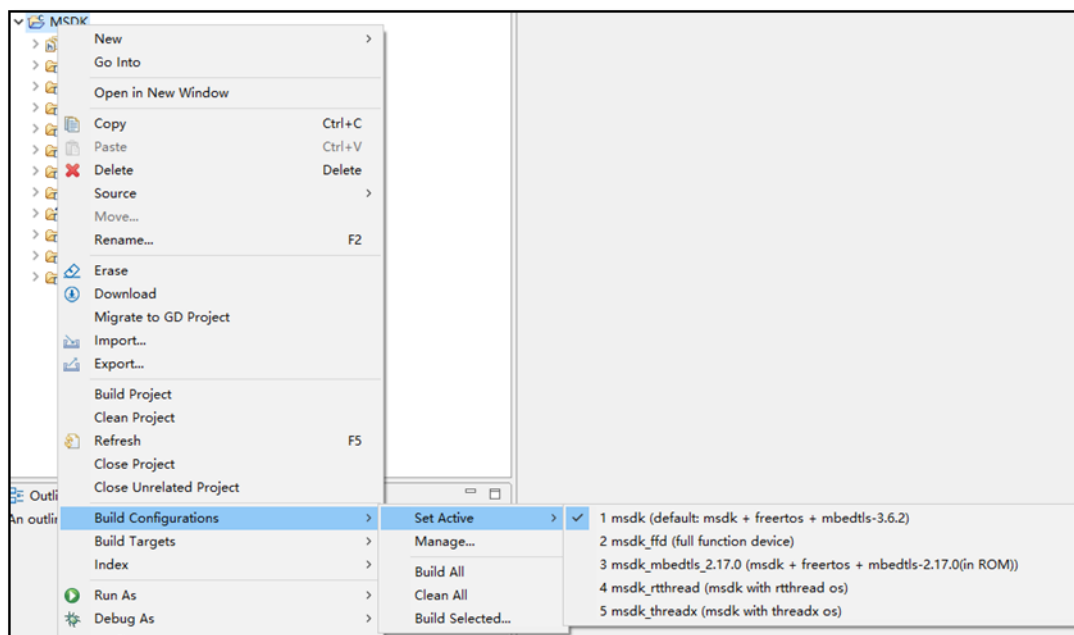
Figure 4-10. MBL compilation result

After the compilation is complete, the script MBL\project\mbl_afterbuild.bat will be automatically called to generate mbl.bin and copied to the directory \scripts\images.

■ Compile the MSDK project

Right-click the project, and click Build Configurations—>Set Active—><target configuration> in order. as shown in **Figure 4-11. target configuration selection**, the default target project is msdk.

Figure 4-11. target configuration selection

Right-click the project again, and click Build Project, The compilation result is as shown in **Figure 4-12. MSDK compilation result**.

Figure 4-12. MSDK compilation result
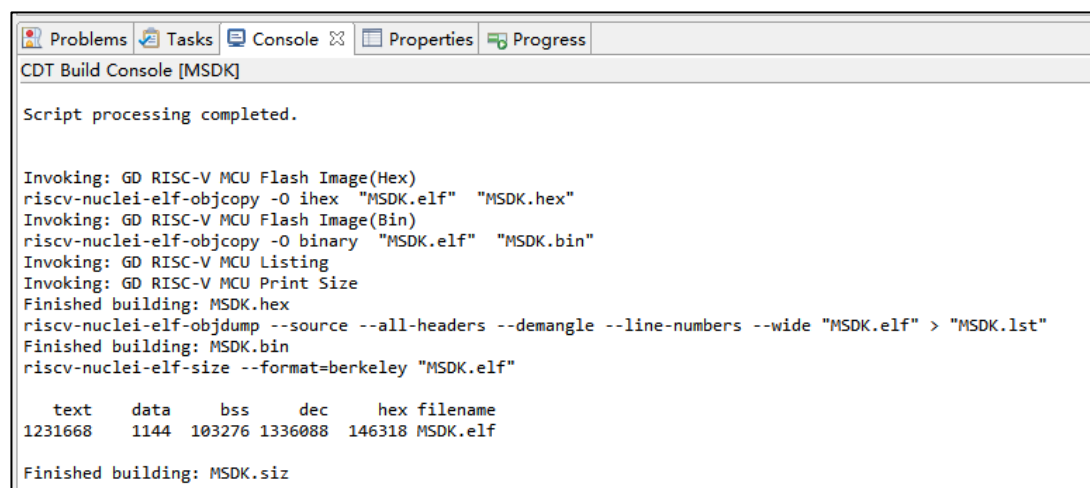
■ Images generated by SDK

After MSDK is compiled, it will call MSDK\projects\ image_afterbuild.bat to generate image-ota.bin and image-all.bin, and copy the generated bin files to \scripts\images, as shown in **Figure 4-13. Images output**.

image-ota.bin is the bin file generated by MSDK project, which can be used for OTA upgrade. image-all.bin is the combination of MBL(mbl.bin) and MSDK(image-ota.bin), the firmware can be used for production, download into FLASH and run.

Figure 4-13. Images output

名称	修改日期	类型	大小
image-all.bin	2024/7/11 14:26	BIN 文件	788 KB
image-ota.bin	2024/7/11 14:26	BIN 文件	748 KB
mbl.bin	2024/7/11 14:19	BIN 文件	17 KB

4.3.   Download firmware

4.3.1.   USB Drive Copy

As shown in **1.4Download interface**, copying the image-all.bin file from GD32VW55x_RELEASE\scripts\images to the Gigadevice drive. This functionality is only supported on the START development board when using the onboard GDLink connection.

4.3.2.   Use afterbuild.bat for downloading

The project supports automatically downloading the image after compilation by invoking a script through afterbuild. The script file is MSDK\projects\image_afterbuild.bat.

At the end of image_afterbuild.bat, there is a section of code configured for automatic image downloading, as shown in **Figure 4-14 Configure image automatic downloading**.

Figure 4-14 Configure image automatic downloading

```
:download
set OPENOCD="%OPENOCD_PATH%\\openocd.exe"
::set LINKCFG="..\\openocd_gdlink.cfg"
set LINKCFG="..\\openocd_jlink.cfg"
@echo on
::%OPENOCD% -f %LINKCFG% -c "program %DOWNLOAD_BIN% 0x0800A000 verify reset exit;"
:end
```

This segment of code utilizes OpenOCD with Jlink/GDLink to perform downloading. By configuring OpenOCD to use different .cfg files, users can choose whether to download via Jlink or GDLink.

When using GDLink to connect the computer and development board, set LINKCFG to openocd_gdlink.cfg. For connections via Jlink, set LINKCFG to openocd_jlink.cfg.

After compilation, Afterbuild will invoke this script to execute the configured commands and complete the corresponding image download (please uncomment the lines within the red box from the figure; this feature is disabled by default).

4.3.3. Using J-Flash Lite for downloading

When using Jlink for debugging and firmware downloading, you can find JFlashLite.exe in the directory: GD32EmbeddedBuilder_v1.4.14.29824\Tools\J-Link. Double-click to open JFlashLite and configure it as shown in *__Figure 4-15 JFlashLite Configuration__*.

Figure 4-15 JFlashLite Configuration
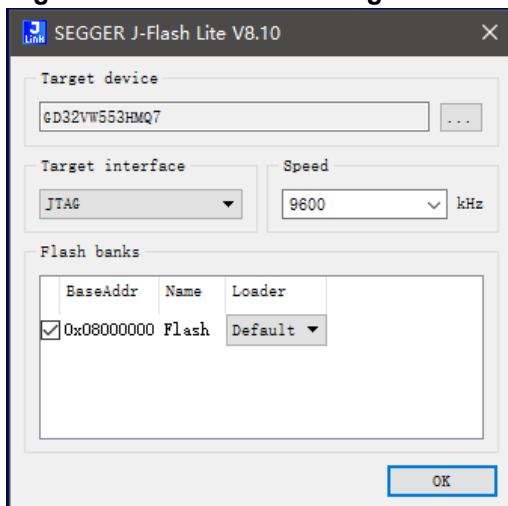
Set the Target device to GD32VW553xxxx, choose the Target interface as JTAG (cJTAG can also be selected, but it is slower), and set the Speed to 9600 kHz. Then click OK.

In the opened interface, as shown in *__Figure 4-16 J-Flash Programming Interface__*, select the Data File as the compiled image-all.bin or image-ota.bin (stored in the directory GD32VW55x_RELEASE_V1.0.xx\scripts\images after compilation).

When selecting image-all.bin, set the Prog. Addr. on the right to 0x08000000.

When selecting image-ota.bin, set the Prog. Addr. on the right to 0x0800A000.

Once the settings are complete, click "Program Device" and wait for the progress bar to finish, which indicates the completion of the programming process.

**Figure 4-16 J-Flash Programming Interface**
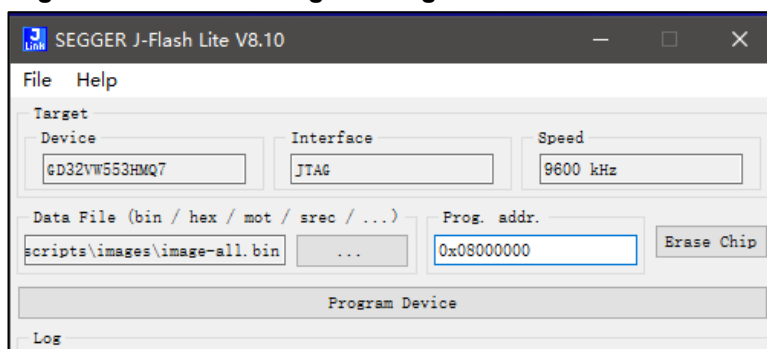
4.4. Debugging

Currently, both the START development board and the EVAL development board feature onboard GDLink, and an external Jlink can also be used for debugging.

The debugging process is described below, and the default project configuration is msdk. If you need to switch to another project configuration, please refer to section *6.3Select different project configurations during debugging* for selecting different project configurations for debugging.
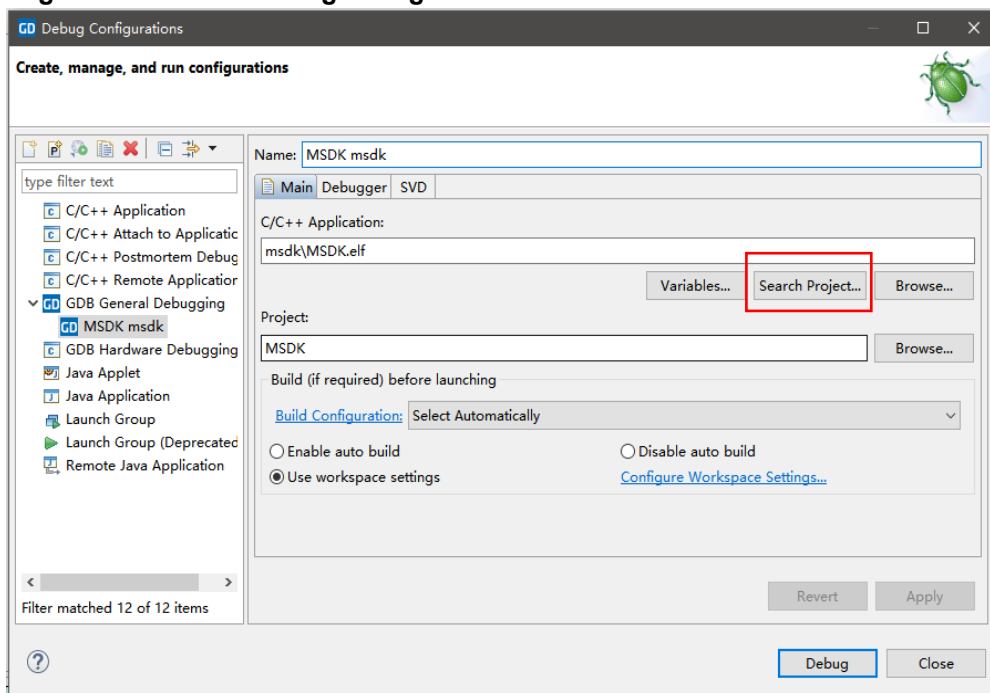
4.4.1. Debugging configuration

Right-click on the MSDK project and click Debug As->Debug Configurations, as shown in *Figure 4-17. Opening the Debug Configuration option*.

**Figure 4-17. Opening the Debug Configuration option**
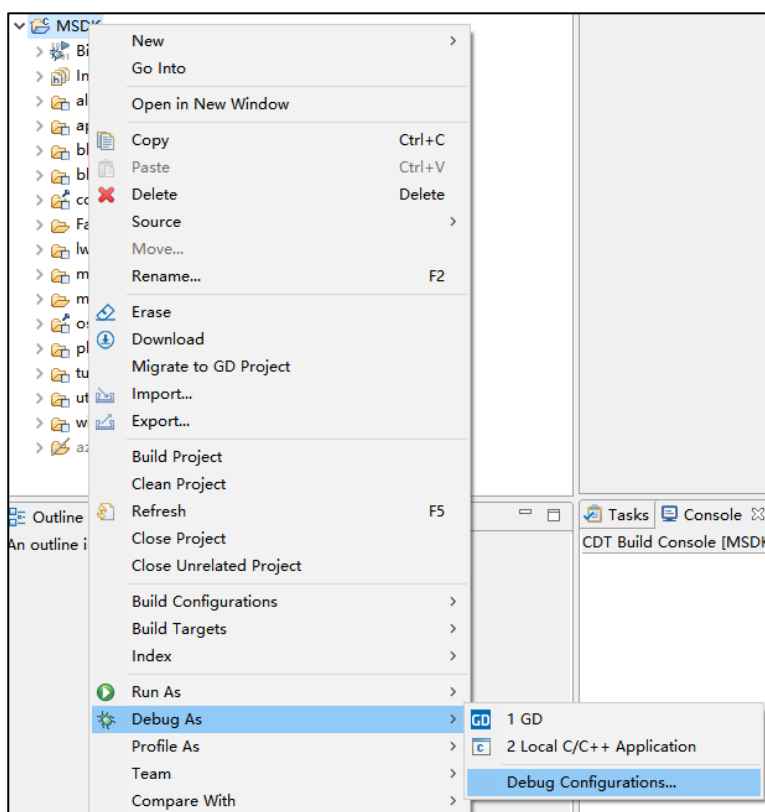
Double-click "GDB General Debugging" on the left, and a Debug configuration will automatically be created, as shown in *Figure 4-18. MSDK debug configuration*. Here, the c/c++ application field has automatically selected msdk\MSDK.elf, which points to the ELF file generated by the configuration to be debugged.

You can check or uncheck "Enable/Disable auto build" to choose whether or not to compile the project before debugging.

Figure 4-18. MSDK debug configuration

4.4.2. Debugging using GDLink

As shown in *Figure 4-19. MSDK Debugging Configuration Interface with openocd*, switch the GDB Server to OpenOCD in the Debugger interface. Additionally, specify the Config Options within the red box as shown in the figure. Afterward, click "Debug" to start debugging. The debugging interface is displayed in *Figure 4-20. MSDK debug interface*.

**Figure 4-19. MSDK Debugging Configuration Interface with openocd**
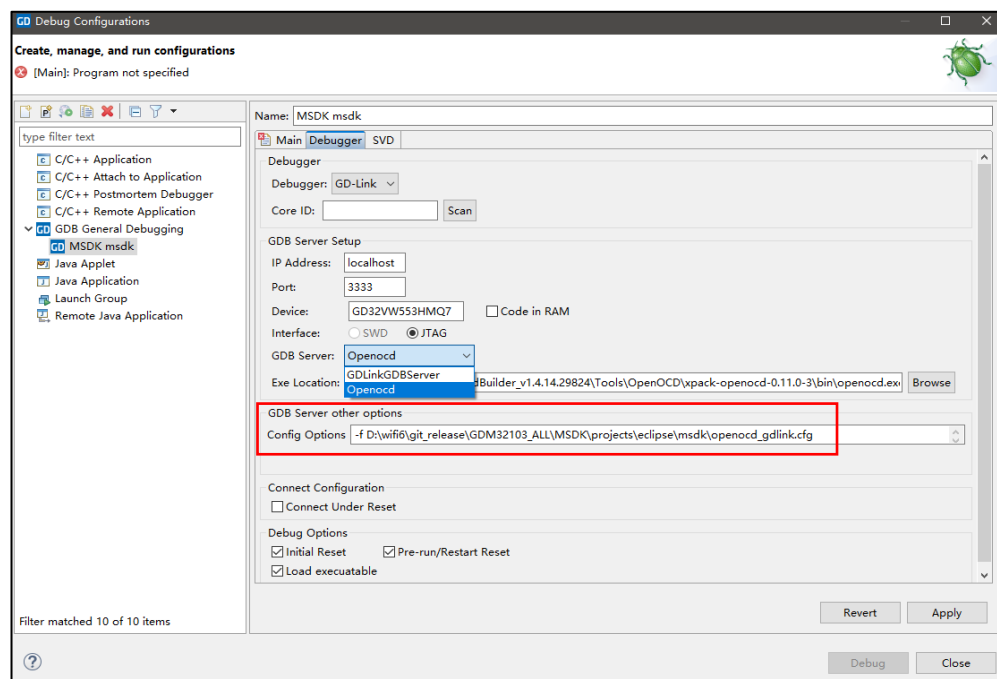
In *Figure 4-19. MSDK Debugging Configuration Interface with openocd*, selecting "Initial

Reset" and "Pre-run/Restart Reset" in the Debug Options will reset the chip at the start of debugging. Choosing "Load executable" will flash the firmware once before debugging begins.

4.4.3. Debugging using Jlink

The GD32VW553 supports JTAG and cJTAG debugging. First, connect the pins of the JLink debugger to the GD32VW553 JTAG pins. Next, replace the cfg file within the red box in the *Figure 4-19. MSDK Debugging Configuration Interface with openocd* with "openocd_jlink.cfg" (this file is located in the directory: MSDK\projects\eclipse\msdk). Then, click "Debug" to enter the debugging process. If driver issues arise during JLink debugging, please refer to *6.4 JLink Driver Replacement*.

Figure 4-20. MSDK debug interface
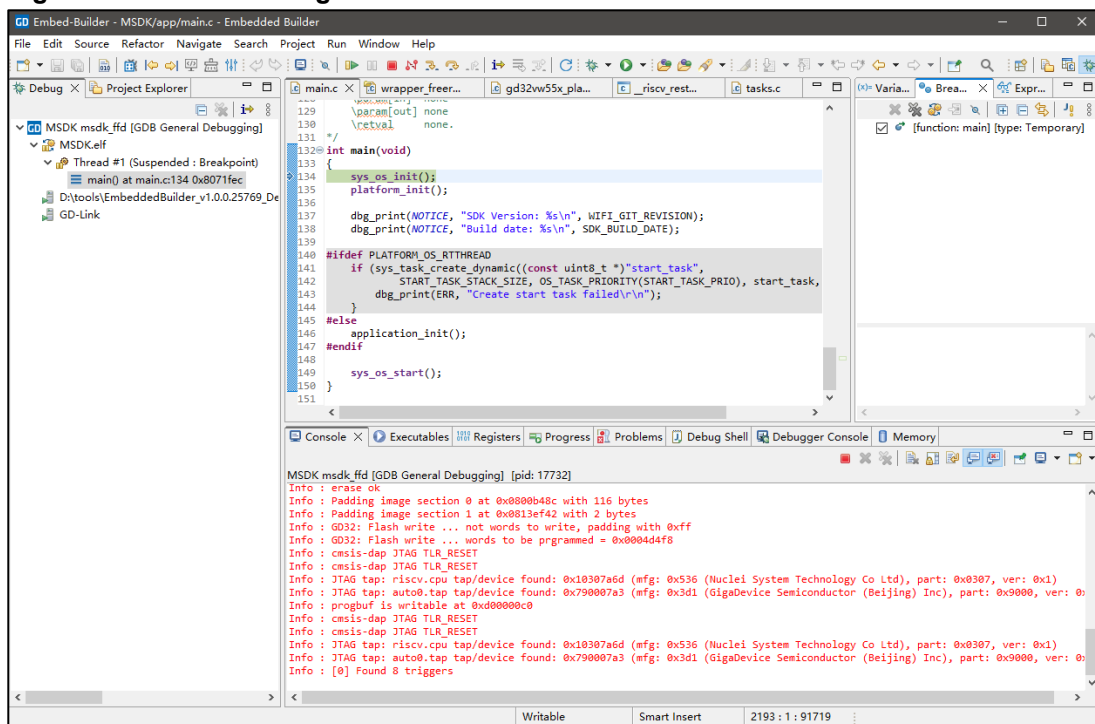
5. SEGGER Embedded Studio IDE project

This chapter introduces how to compile and debug the SDK under SEGGER Embedded Studio IDE.

## 5.1. Open projects

■ Open MBL project

Open the directory: GD32VW55x_RELEASE\MBL\project\segger, double click MBL.emProject to open the MBL SES project. The opened project is shown in **_Figure 5-1. MBL SES Project Project Interface_**.

Figure 5-1. MBL SES Project Project Interface
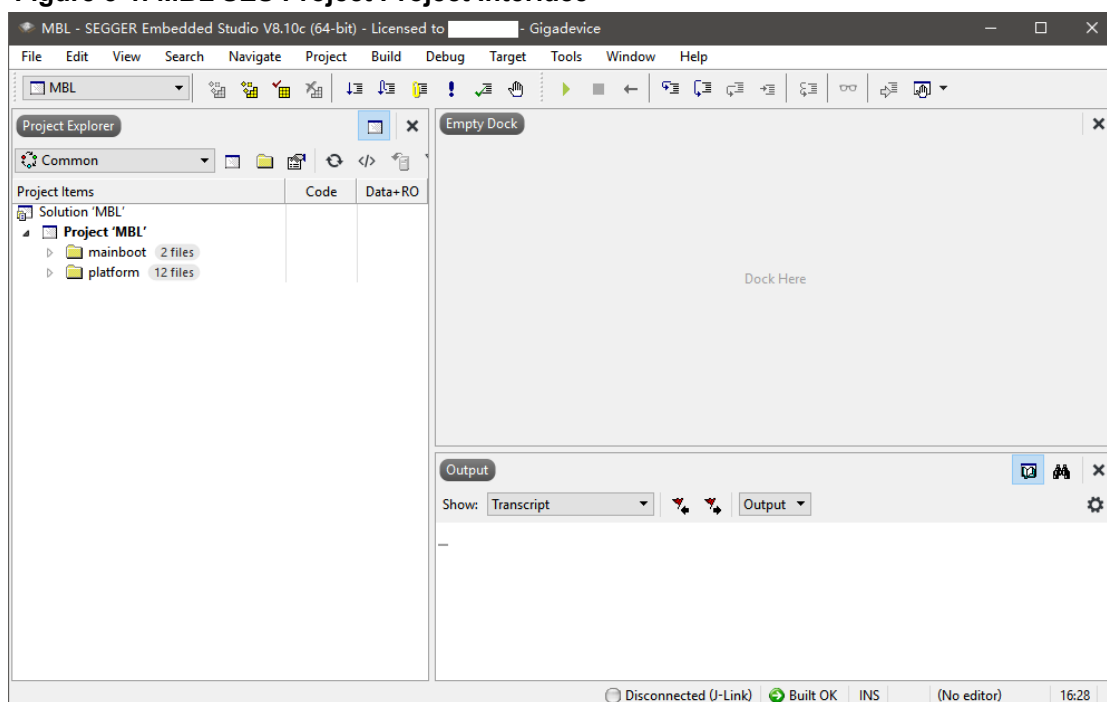
■ Open MSDK project

Open the directory: GD32VW55x_RELEASE\MSDK\projects\segger, double-click on the MSDK.emProject to open the MSDK project, open the project as **_Figure 5-2. MSDK SES Project Interface_** shown.

Figure 5-2. MSDK SES Project Interface
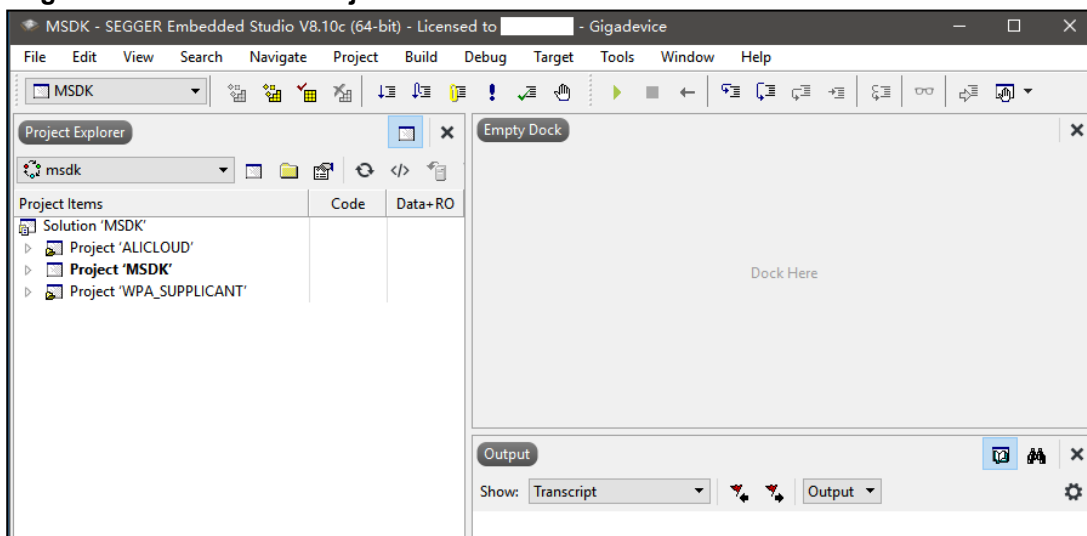
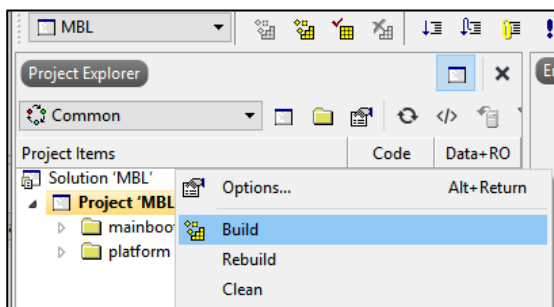## 5.2. Compilation

■ SES build tool configuration

SES compiles the GD32VW55x project using the riscv32-none-elf toolchain by default. In order to better support the extended instruction set of riscv, it needs to be compiled using the nuclei toolchain: riscv-nuclei-elf. The compilation tool can be obtained by contacting sales or FAE. The details of the toolchain are shown in *Figure 5-3. nuclei toolchain content*. Where the Segger_IDE is the SES IDE installation directory.
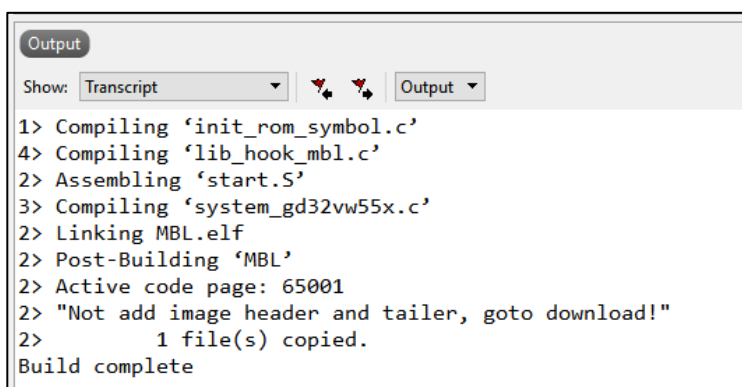
Figure 5-3. nuclei toolchain content

■ Compile the MBL project

Right-click the project and click build to guild MBL, as shown in *Figure 5-4. Compiling the MBL project*; or click Build->Build MBL in the menu bar.

Figure 5-4. Compiling the MBL project

The compilation result is as shown in **_Figure 5-5. MBL compilation result_**.

Figure 5-5. MBL compilation result

After the compilation is complete, the script MBL\project\mbl_afterbuild.bat will be automatically called to generate mbl.bin and copied to the directory \scripts\images.

■ Compile the MSDK project

Right-click Project 'MSDK' and click Build, as shown in **_Figure 5-6. Compile MSDK project_**.

Figure 5-6. Compile MSDK project
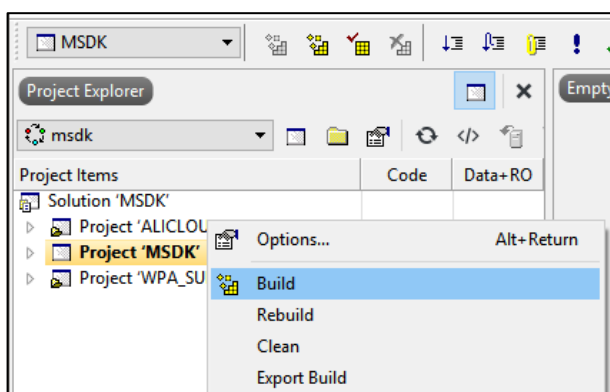
■ Configuration selection of MSDK

MSDK configuration switch as shown in **_Figure 5-7 MSDK Project Configuration Options_**. MSDK SES project only supports msdk, msdk_ffd and msdk_mbedtls_2.17.0; if you need to use the configuration of msdk_threadx, msdk_ffd_threadx please use the GD32 EmbeddedBuilder IDE project or wait for subsequent updates.

Figure 5-7 MSDK Project Configuration Options
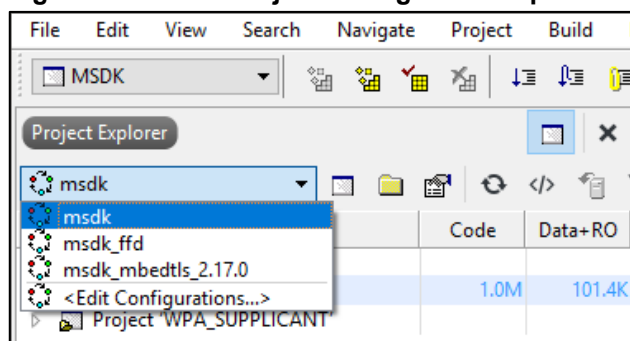
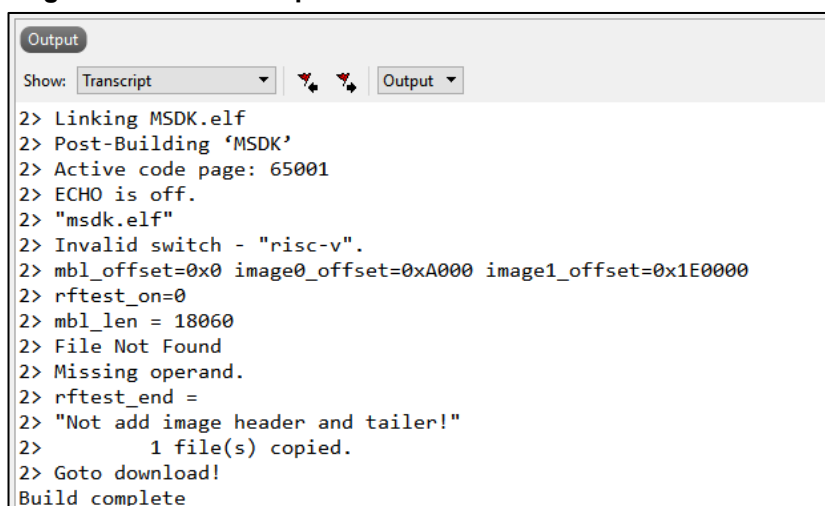After selecting the corresponding configuration, right-click the project and click Build, the compilation result is shown in **Figure 5-8 MSDK compilation result**.

Figure 5-8 MSDK compilation result

■   Image generated by SDK

After MSDK is compiled, it will call MSDK\projects\image_afterbuild.bat to generate image-ota.bin and image-all.bin, and copy the generated bin files to \scripts\images, as shown in **Figure 5-9. Images output**.

image-ota.bin is the bin file generated by MSDK project, which can be used for OTA upgrade. image-all.bin is the combination of MBL(mbl.bin) and MSDK(image-ota.bin), the firmware can be used for production, download into flash and run.
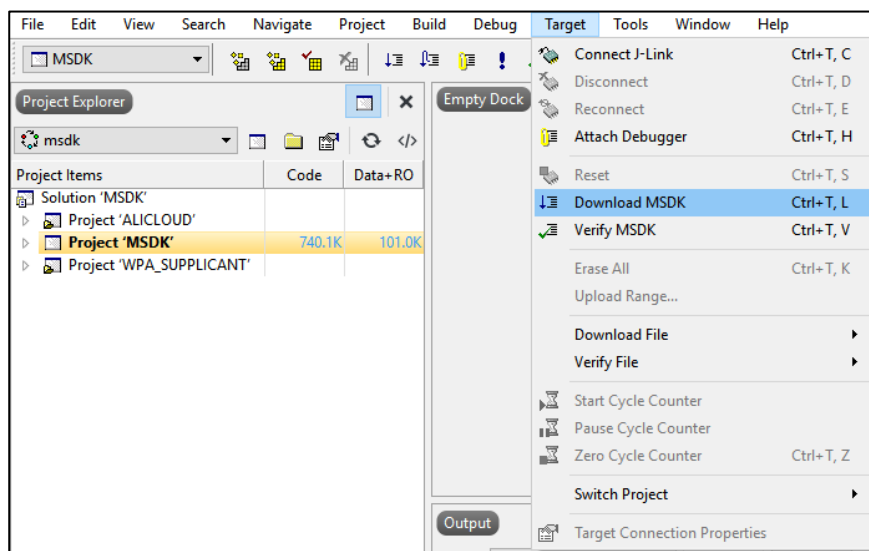
Figure 5-9. Images output

5.3.   Download firmware

Refer to **1.4 Download interface**, copy GD32VW55x_RELEASE\scripts\images\image-

all.bin to the Gigadevice disc to download it. Or download it by clicking Target->Download MSDK in the menu bar, as shown in *__Fogure 5-10 SES IDE image download__*.

Fogure 5-10 SES IDE image download

5.4.   Debugging

■   Debugging configuration

SES IDE recommends using J-link to debug, and J-link driver version at least V7.92o, this version of J-link driver support GD32VW55x chip.

The project has been configured with Debug information by default, if you need to change it, right-click on the MSDK project, click Options to open the configuration interface, you can modify the Debugger and JLink under the Debug option, as shown in *__Figure 5-11. MSDK SES Project Configuration Interface__*.

Figure 5-11. MSDK SES Project Configuration Interface
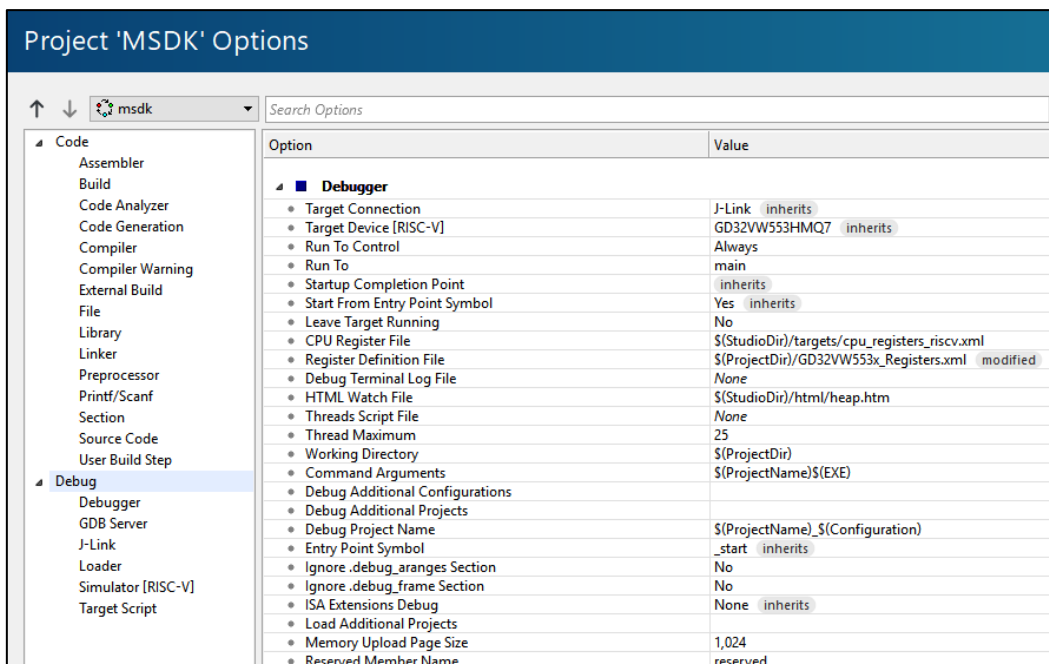
■   Start Debugging

Click Debug->GO in the menu bar to debug, click and wait for the image downloading to complete and enter the interface shown in .

Figure 5-12. SES IDE Debug Interface

6. FAQ

6.1. No image error

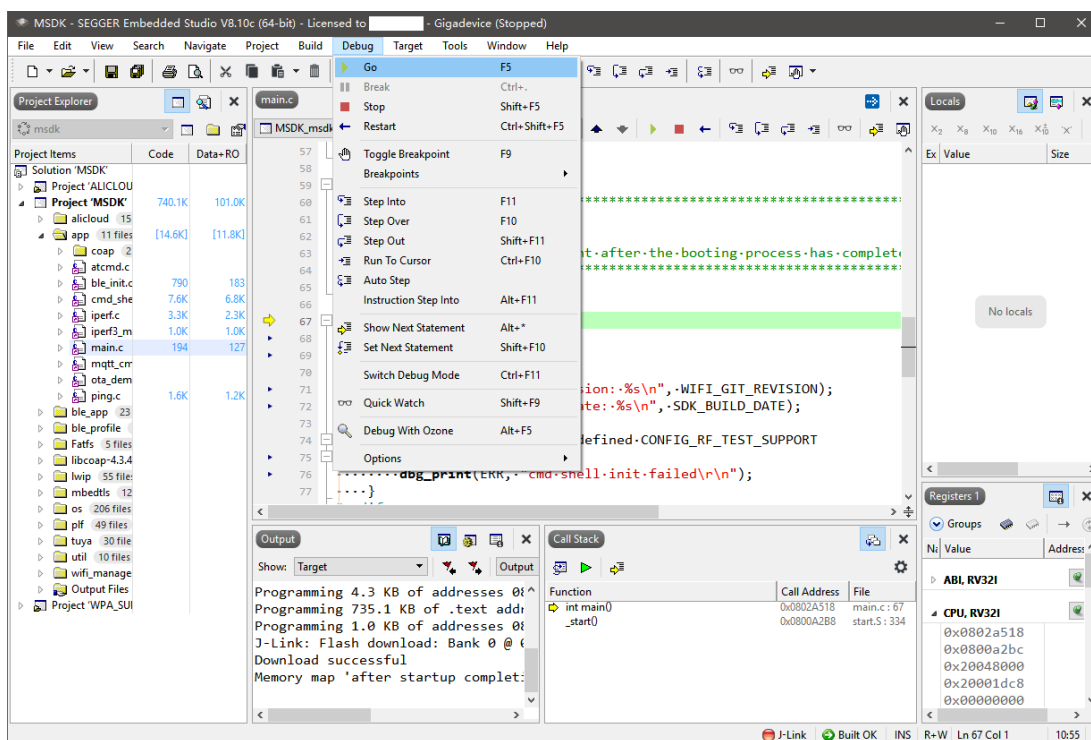Print ERR: No image to boot (ret = -5).

Reason: An error occurs during the previous boot of WIFI_IOT, and the MBL records operation exception of the IMAGE. If another IMAGE is not downloaded or also has a boot exception, this message will be printed. In other words, the MBL believes that there is no valid IMAGE to jump to, and the boot fails.

Solution: Download the MBL again. After that, the IMAGE status will be cleared.

6.2. Code running in SRAM

To run programs faster to achieve higher performance, move them to the SRAM.

Open GD32VW55x_RELEASE\MSDK\plf\riscv\env\gd32vw55x.ld, and find the line ".code_to_sram:". The code in the braces runs in the SRAM. To add new content, add it at the end of the code. Refer to existing files for the format, for exemple:

KEEP (*port.o* (.text* .rodata*))

It is to put the entire port.c file in the SRAM and run it. For example:

KEEP (*tasks.o* (.text.xTaskIncrementTick))

It is to put the xTaskIncrementTick () function in tasks.c in the SRAM and run it.

6.3. Select different project configurations during debugging

The MSDK project supports multiple configurations (refer to ***3.2.6Configuration Selection***). During debugging, you need to select the appropriate configuration.

The specific operation is as follows: Click the "Search Project" button within the red box shown in ***Figure 4-18. MSDK debug configuration***. This opens the interface shown in ***Figure 6-1 Select Project Configuration for Debugging***. Double-click the configuration you want to debug within the Qualifier box below (note that you need to compile the corresponding configuration first for the option to appear).

**Figure 6-1 Select Project Configuration for Debugging**
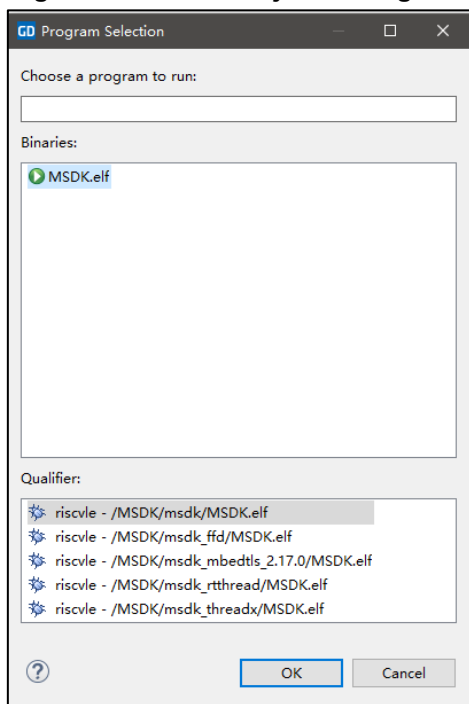
6.4. JLink Driver Replacement

When using OpenOCD+JLink debugging in an Embedded Builder project, if encountering the issue "Error: No J-Link device found," JLink drivers need to be replaced. The steps are as follows:

1. Use administrator privileges to open the zadig.exe file (official website: https://zadig.akeo.ie). Click "Options" and check "List All Devices," as shown in *Figure 6-2 Zadig Options Selection*.

Figure 6-2 Zadig Options Selection
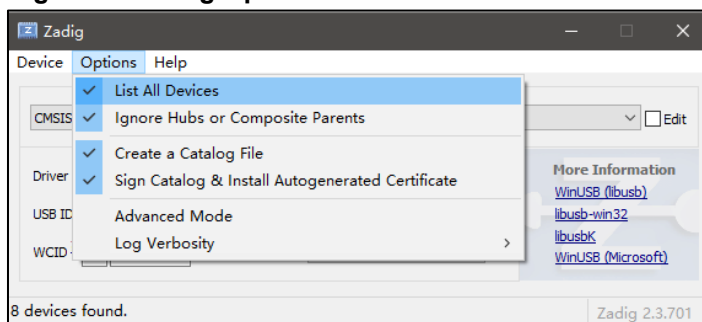
2. Select "JLink devices" from the dropdown menu, as shown in *Figure 6-3 Replace JLink Driver*, where the BULK interface is displayed. Click "Replace Driver" to replace the JLink driver with WinUSB.

Figure 6-3 Replace JLink Driver
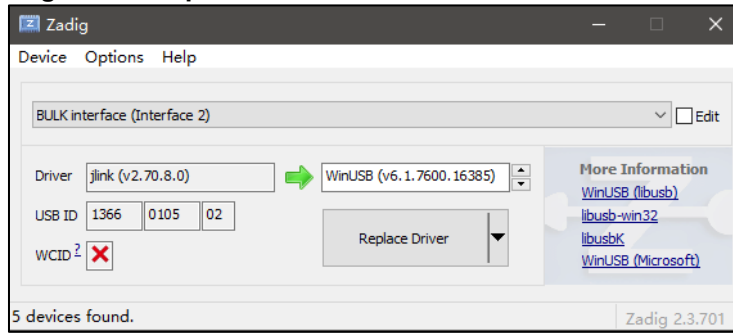
3.   After the replacement is complete, unplug and replug the JLink device. Then use JLink for debugging, and there will be no driver issues.

7.   Revision history

Table 7-1. Revision history

Revision No.	Description	Date
1.0	Initial release	Nov.24.2023
1.1	Chapter 2 revision	Jan.26.2024
1.2	SES IDE project added, GD32 Eclipse IDE updated to GD32 Embedded Builder	July.17. 2024
1.3	Update some diagrams to be consistent with SDK1.0.3	Apr.8.2025
1.3a	Update the development board images and add firmware downloads	May.15.2025

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